

Product Data Sheet & General Processing Conditions

RTP 199 X 149322 B
Polypropylene (PP)
Glass Fiber
Chemically Coupled
Low Density
Preliminary Datasheet

PROPERTIES & AVERAGE VALUES OF INJECTION MOLDED SPECIMENS

PERMANENCE		STANDARD
Primary Additive	30 %	
Density	1.04 g/cm ³	ISO 1183
MECHANICAL		
Impact Strength, Charpy		
Notched, 4 mm thickness	8 kJ/m²	ISO 179/1eA
Tensile Strength	82 MPa	ISO 527
Flexural Modulus	6500 MPa	ISO 178
PROPERTY NOTES		
Data herein is typical and not to be construed as specifications. Unless otherwise specified, all data listed is for natural or black colo	red materials. Pigments can affect propert	ies.
GENERAL PROCESSING FOR INJECTION MOLDING		
Injection Pressure	70 - 105 MPa	
Injection Pressure	680 - 1030 bar	
Melt Temperature	190 - 230 °C	
Mold Temperature	30 - 65 °C	
Drying	2 hrs @ 80 °C	
PROCESSING NOTES		

21 Dec 2018 BWA

This information is intended to be used only as a guideline for designers and processors of modified thermoplastics. Because design and processing is complex, a set solution will not solve all problems. Observation on a "trial and error" basis may be required to achieve desired results.

Data are obtained from specimens molded under carefully controlled conditions from representative samples of the compound described herein.

Properties may be materially affected by molding techniques applied and by the size and shape of the item molded. No assurance can be implied that all molded articles will have the same properties as those listed.

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